Overview

HP ProBook 430 G6 Notebook PC



Left

- 1. Internal microphones (2)
- 2. Webcam
- 3. Webcam LED
- 4. Clickpad
- 5. Hard drive LED

- 6. SD Card reader
- 7. Thermal vent
- 8. USB 3.1 Gen 1 port
- 9. Security lock slot (Lock sold separately)
- 10. Power button

Overview



Right

- 1. Power connector
- 2. USB Type-C[™] 3.1 Gen 1 port
- 3. Ethernet port (RJ-45)
- 4. HDMI port (Cable not included)

- 5. USB 3.1 Gen 1 port
- 6. Headphone/microphone combo jack
- 7. HP Fingerprint Sensor



Overview

At a Glance

- Preinstalled with Windows 10 versions or FreeDOS 3.0
- Choice of 8th Generation Intel® Core™ i7, i5, i3 processors
- Display include your choice of 33.8 cm (13.3") diagonal HD, Ultra Wide Viewing Angle FHD, Touch or Non-Touch screen
- Integrated Intel® HD Graphics 610 and intel® UHD 620
- Enhanced security features including TPM2.0, HP BIOSphere, Hardware enforced Firmware Protection, optional Fingerprint sensor, and optional IR camera
- Passed 19 items of MIL-STD 810G testing plus an additional 120,000 hours of reliability testing through HP's Total Test Process¹
- Weight starting at 3.28 lbs (1.49 kgs)
- HP Long-Life Rechargeable battery, with HP Fast Charge Technology recharges 50% in 30 minutes²
- Supports wireless LAN and wireless WWAN options for connectivity on the go
- Up to 512 GB Solid State Drives or 1 TB Hard Drive
- Up to 32 GB total system memory
- 720p HD webcam, IR camera for face authentication with Windows Hello
- Spill-resistant and optional backlit Keyboard, and Clickpad with multi-touch gestures enabled, taps enabled as default
- Enjoy the rich conferencing experience of the Skype for Business™ Certified HP ProBook 430

- MIL STD 810G testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements
 or for military use. Test results are not a guarantee of future performance under these test conditions. Damage
 under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection
 Care Pack.
- 2. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Technical Specifications

PRODUCT NAMES

HP ProBook 430 G6 Notebook PC

OPERATING SYSTEMS

Preinstalled Windows 10 Pro 64¹

Windows 10 Pro 64 (National Academic only)²

Windows 10 Home 641

Windows 10 Home Single Language 64¹ Windows 10 China Government Edition

FreeDOS 3.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

PROCESSORS

Intel® Core™ i7-8565U with Intel® UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6}

Intel® Core™ i5-8265U with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6}

Intel® Core™ i3-8145U with Intel® UHD Graphics 620 (2.1 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 4 MB L3 cache, 2 cores)^{3,4,5,6}

Intel® Core™ i7+ 8565U processor (Core™ i7 and 16 GB Intel® Optane™ memory) with Intel® UHD Graphics 620 (1.8 GHz base frequency, up to 4.6 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{3,4,5,6,7}

Intel® Core™ i5+ 8265U processor (Core™ i5 and 16 GB Intel® Optane™ memory) with Intel® UHD Graphics 620 (1.6 GHz base frequency, up to 3.9 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{3,4,5,6,7}

Intel® Celeron® 4205U processor with Intel® HD Graphics 610 (1.8 GHz base frequency, 2 MB L3 cache, 2 cores)^{3,4,5,6} Intel® Pentium® 5405U processor with Intel® HD Graphics 610 (2.3 GHz base frequency, 2 MB L3 cache, 2 cores)^{3,4,5,6}

Processors Family

8th Generation Intel® Core™ i7 processor (i7-8565U)⁶ 8th Generation Intel® Core™ i5 processor (i5-8265U)⁶ 8th Generation Intel® Core™ i3 processor (i3-8145U)⁶ Intel® Pentium® processor (5405U)⁶ Intel® Celeron® processor (4205U)⁶

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.



Technical Specifications

- 6. NOTE: In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.
- 7. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system and requires configuration with an optional Intel® Core™ i(5 or 7)+ processor.

CHIPSET

Integrated with processor

GRAPHICS

Integrated

Intel® UHD graphics 6208

8. HD content required to view HD images.

DISPLAYS

Internal

Non-Touch

33.8 cm (13.3") diagonal HD SVA eDP anti-glare LED-backlit Ultraslim, 220 cd/m 2 , 67% sRGB for two WLAN antennas (1366 x 768) 8,10

33.8 cm (13.3") diagonal HD SVA eDP anti-glare LED-backlit Ultraslim, 220 cd/m 2 , 67% sRGB for HD camera and two WLAN antennas (1366 x 768) 8,10

33.8 cm (13.3") diagonal HD SVA eDP anti-glare LED-backlit Ultraslim, 220 cd/m 2 , 67% sRGB for HD+IR camera and two WLAN antennas (1366 x 768) 8,10

33.8 cm (13.3") diagonal HD SVA eDP anti-glare LED-backlit Ultraslim, 220 cd/m 2 , 67% sRGB for HD camera, WWAN and two WLAN antennas (1366 x 768) 8,10

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/ m^2 , 67% sRGB for HD camera and two WLAN antennas $(1920 \times 1080)^{8,10}$

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m 2 , 67% sRGB for HD+IR camera and two WLAN antennas (1920 x 1080) 8,10

33.8 cm (13.3") diagonal FHD UWVA eDP anti-glare LED-backlit slim, 220 cd/m 2 , 67% sRGB for HD camera, WWAN and two WLAN antennas (1920 x 1080) 8,10

Touch

33.8 cm (13.3") diagonal HD SVA eDP LED-backlit Ultraslim touch screen, 220 cd/m 2 , 67% sRGB for HD camera and two WLAN antennas (1366 x 768) 8,9,10

33.8 cm (13.3") diagonal FHD UWVA eDP LED-backlit slim touch screen, 220 cd/m 2 , 67% sRGB for HD camera and two WLAN antennas (1920 x 1080) 8,9,10

33.8 cm (13.3") diagonal FHD UWVA eDP LED-backlit slim touch screen, 220 cd/m 2 , 67% sRGB for HD camera, WWAN and two WLAN antennas (1920 x 1080) 8,9,10

HDMI

Supports resolutions up to 4K 30Hz

- 8. HD content required to view HD images.
- 9. Sold separately or as an optional feature.
- 10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.



Technical Specifications

Docking station model	Total number of supported displays (incl. the notebook display)	Max. resolutions supported	Dock Connectors	Technical limitations
HP Thunderbolt Dock 120W G2	3	Dual 4k @60Hz	2xDP, 1xVGA, 1xTB, 1xUSB-C alt- mode	Dual 4k only with one display in to DP and + TB port or USB-C alt mode + TB port
HP USB-C Dock G4	3	Dual 2K @ 60Hz Single 4K @ 60Hz (3840 x 1440)	1xHDMI, 2xDP	
HP USB-C Universal Dock	3	Dual 4K @ 60Hz Single 5K @ 60Hz	2xDP	
HP USB-C Travel Dock	2	Single 2K @ 60Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time
HP USB-C Mini Dock	2	Single 4K @ 30Hz	1xHDMI, 1xVGA	Single external display Only HDMI or VGA at the time

STORAGE AND DRIVES

Primary Storage

500 GB 7200 rpm SATA¹¹ 1 TB 5400 rpm SATA¹¹

Primary M.2 Storage

128 GB M.2 SATA TLC Solid State Drive¹¹
256 GB PCIe® NVMe™ M.2 Value Solid State Drive¹¹
512 GB PCIe® NVMe™ M.2 TLC Solid State Drive¹¹
512 GB PCIe® NVMe™ M.2 Value Solid State Drive¹¹

11. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

NOTE: PCIe SSD not available for Celeron

MEMORY

Memory

32 GB DDR4-2400 SDRAM (2 x 16 GB)¹²
16 GB DDR4-2400 SDRAM (1 x 16 GB)
16 GB DDR4-2400 SDRAM (2 x 8 GB)¹²
12 GB DDR4- 2400 SDRAM (4 GB and 8 GB (1 x 8 GB)¹²
8 GB DDR4-2400 SDRAM (1 x 8 GB)
8 GB DDR4-2400 SDRAM (2 x 4 GB)¹²



Technical Specifications

4 GB DDR4-2400 SDRAM (1 x 4 GB)

Maximum

32 GB DDR4-2400 SDRAM12

Memory Slots

2 SODIMM Both slots are customer accessible / upgradeable DDR4 PC4 SODIMMS, system runs at 2400 Supports Dual Channel Memory

12. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

Wireless LAN (WLAN)

Realtek 802.11ac (2x2) WLAN and Bluetooth® 4.2 Combo¹³ Intel® Dual Band Wireless-AC 9560 802.11ac (2x2) WLAN and Bluetooth® 5.0 Combo, non-vPro™¹³

Broadband Wireless (WWAN)

Intel® XMM™ 7262 LTE-Advanced (Cat6)¹⁴ Intel® XMM™ 7360 LTE-Advanced (Cat9)¹⁴

Ethernet

Realtek RTL8111HSH-CG 10/100/1000 GbE NIC15

- 13. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.
- 14. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.
- 15. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

AUDIO/MULTIMEDIA

Audio

Integrated microphone (Mono or Dual Array)
2 Integrated stereo speakers

Camera

720p HD camera⁸ 720p HD camera+IR Camera^{8,9}

- 8. HD content required to view HD images.
- 9. Sold separately or as an optional feature.



Technical Specifications

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Keyboard, spill resistant with optional backlit function

Pointing Device

Clickpad with multi-touch gesture support

Function Keys

ESC: system information

F1 - Display Switching

F2 - Blank

F3 - Brightness Down

F4 - Brightness Up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Blank or Backlit Toggle

F10 - numlk

F11 - Wireless

F12 - Sleep

Hidden Functions

Fn+R - Break

Fn+S - Sys Rq

Fn+C - Scroll Lock

Fn+E - Insert

SOFTWARE AND SECURITY

BIOS

HP BIOSphere Gen416

HP DriveLock & Automatic DriveLock

BIOS Update via Network

Secure Erase¹⁷

Absolute Persistence Module¹⁸

Pre-boot Authentication

HP Wireless Wakeup

Software

HP Native Miracast Support¹⁹

HP LAN-Wireless Protection

HP Connection Optimizer

HP 3D DriveGuard

HP Hotkey Support - CMIT

HP Jumpstart

HP Support Assistant²⁰



Technical Specifications

HP Noise Cancellation Software
HP Host Based MAC Address Manager
Buy Office (sold separately)

Manageability Features

HP Driver Packs²¹

HP System Software Manager (SSM)

HP BIOS Config Utility (BCU)

HP Client Catalog

HP Manageability Integration Kit Gen2²²

Ivanti Management Suite²³

Client Security Software

- HP Client Security Suite Gen424 including:
- HP Security Manager²⁵ (including Credential Manager, HP Password Manager, HP Spare Key)
- HP Fingerprint Sensor²⁶
- HP Device Access Manager²⁷
- HP Power On Authentication

Windows Defender²⁸

Security Management

Secure Erase¹⁷

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)²⁹

SATA 0,1 port disablement (viaBIOS)

RAID configurations³⁰

Serial, USB enable/disable (viaBIOS)

Power-on password (viaBIOS)

Setup password (viaBIOS)

Support for chassis padlocks and cable lock devices

Integrated hood sensor

HP Sure Click³¹

- 16. HP BIOSphere Gen4 requires Intel(R) or AMD 8th Gen processors. Features may vary depending on the platform and configurations.
- 17. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method.
- 18. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.



Technical Specifications

- 19. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming
- 20. HP Support Assistant requires Windows and Internet access.
- 21. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 22. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- 23. Ivanti Management Suite subscription required
- 24. HP Client Security Suite Gen 4 requires Windows and Intel® or AMD 8th generation processors.
- 25. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- 26. HP Fingerprint Sensor sold separately or as an optional feature.
- 27. HP Device Access Manager requires HP Client Security Suite Gen4.
- 28. Windows Defender Opt in and internet connection required for updates.
- 29. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).
- 30. RAID configuration is optional and does require a second hard drive.
- 31. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

POWER

HP Smart 65 W External AC power adapter³²
HP Smart 65 W EM External AC power adapter³²
HP Smart 65 W USB Type-C[™] adapter³²
HP Smart 45 W External AC power adapter³²
HP Smart 45 W USB Type-C[™] adapter³²

Primary Battery

HP Long Life 3-cell, 45 Wh Li-ion³³

Power Cord

3-wire plug - 1m³²
3-wire plug - 1.8m³²
2-wire plug - 1m³²
Duckhead power cord- 1m³²
Duckhead power cord- 1.8m³²

Battery Life

Up to 14 hours 34

Battery Weight

0.49 lb 0.22 kg

- 32. Availability may vary by country.
- 33. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 34. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.



Technical Specifications

WEIGHTS & DIMENSIONS

Weight

Starting at 3.28 lb³⁵ Starting at 1.49 kg³⁵

Dimensions (w x d x h)

12.15 x 9.09 x 0.71 in 30.85 x 23.1 x 1.8 cm

35. Weight will vary by configuration.

PORTS/SLOTS

Ports

1 USB 3.1 Type-C™ Gen 1 (Power delivery, DisplayPort™)

1 USB 3.1 Gen 1

1 USB 3.1 (Powered port)

1 HDMI 1.4b36

1 RJ-45

1 AC power

1 Headphone/microphone combo jack

Expansion Slots

1 SD

Supports SD, SDHC, SDXC

36. HDMI cable sold separately.

SERVICE AND SUPPORT

HP Services offers 3-year and 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty except for Long Life Batteries which will have same 1-year or 3-year limited warranty as the platform. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.37

37. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Technical Specifications

ENVIRONMENTAL & INDUSTRY

НР Рповоок 430 G6 **N**отевоок **P**C

This product has received or is in the process of being certified to the following approvals and m be labeled with one or more of these marks:				
•EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in				
your country. •TCO or TCO Certified Edge				
		5.14 W		
2.84 W	2.79 W	2.77 W		
0.61 W	0.64 W	0.61 W		
0.38 W	0.42 W	0.38 W		
family. HP computers marked with the ENERGY STAR® Logo are compliant with the appendix commental Protection Agency (EPA) ENERGY STAR® specifications for computers. I family does not offer ENERGY STAR® compliant configurations, then energy efficiency for a typically configured PC featuring a hard disk drive, a high efficiency power supply				
		100VAC, 60Hz		
18 BTU/hr	18 BTU/hr	18 BTU/hr		
10 BTU/hr	10 BTU/hr	9 BTU/hr		
2 BTU/hr	2 BTU/hr	2 BTU/hr		
1 BTU/hr	1 BTU/hr	1 BTU/hr		
Heat dissipation is calculated base for one hour.	ed on the measured watt	s, assuming the service level is attained		
Sound Power		Sound Pressure		
(L _{WAd} , bels)		(L _{pAm} , decibels)		
2.7		24.2		
2.8		25.1		
features and/or components cont • 3 USB ports • 1 PC card slot (type I/II) • 1 ExpressCard/54 slot • 1 IEEE 1394 Port • 2 SODIMM memory slots	ained in the product may			
	be labeled with one or more of the *IT ECO declaration *US ENERGY STAR® *EPEAT® Gold registered in the Un your country. *TCO or TCO Certified Edge The configuration used for the End Notebook model is based on a Tyr 115VAC, 60Hz 5.17 W 2.84 W 0.61 W 0.38 W Energy efficiency data listed is for family. HP computers marked with Environmental Protection Agency family does not offer ENERGY STA for a typically configured PC feature Microsoft Windows® operating system 115VAC, 60Hz 18 BTU/hr 10 BTU/hr 10 BTU/hr Heat dissipation is calculated base for one hour. Sound Power (Lwad, bels) 2.7 2.8 This product can be upgraded, post features and/or components cont • 3 USB ports • 1 PC card slot (type I/II) • 1 ExpressCard/54 slot • 1 IEEE 1394 Port • 2 SODIMM memory slots • Optional expansion base docking • 1 multi-bay II storage port	be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® *EPEAT® Gold registered in the United States. See http://w your country. *TCO or TCO Certified Edge The configuration used for the Energy Consumption and Do Notebook model is based on a Typically Configured Notebook model is based on the ENERGY STAR® compfamily. HP computers marked with the ENERGY STAR® compliant configuration a typically configured PC featuring a hard disk drive, a holicopy Microsoft Windows® operating system. **Insuration**		



Technical Specifications

		re available throughout the warranty period and or for up	to "5" years after the end of		
	production.				
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC				
	Batteries used in the product do not contain:				
	Mercury greater the 1 ppm by weight				
	Mercury greater the I ppm by weight Cadmium greater than 20ppm by weight				
	Caumum greater than zoppin by weight				
	Battery size: CR2032 (coin cell)				
	Battery type: lithium/manganese dioxide				
Additional Information	2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE)				
	Directive – 2002/96/EC.				
		• This product is in compliance with California Proposition 65 (State of California; Safe Drinking			
		Water and Toxic Enforcement Act of 1986).			
	• This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd</gold>				
		party option store for solar generator accessories at http://www.hp.com/go/options			
		• Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.			
		t contains 0% post-consumer recycled plastic (by wt.)	•		
	• This produc	t is 95.1% recycle-able when properly disposed of at end	of life.		
Packaging Materials	External:	PAPER/Corrugated	281 g		
	Internal:	PLASTIC/Polyethylene Expanded - EPE	62 g		
		PLASTIC/Polyethylene low density – LDPE	9 g		
	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.				
	Chlorinated Formaldehy Halogenate Lead carbon Lead and Le Mercuric Ox Nickel – fini carried by the Ozone Depl Polybromin Polybromin Polychlorin Polychlorin Polyvinyl Cl	Paraffins yde d Diphenyl Methanes nates and sulfates ead compounds ide Batteries shes must not be used on the external surface designed to e user. eting Substances ated Biphenyls (PBBs) ated Biphenyl Ethers (PBBEs) ated Biphenyl Oxides (PBBOs) ated Biphenyl (PCB) ated Terphenyls (PCT) nloride (PVC) — except for wires and cables, and certain ret			
	Chlorinated Formaldehy Halogenate Lead carbon Lead and Le Mercuric Ox Nickel – finicarried by the Ozone Depl Polybromin Polybromin Polychlorin Polychlorin Radioactive Radioactive	Paraffins Inde Ide Id Diphenyl Methanes Inates and sulfates Ide Batteries Ishes must not be used on the external surface designed to Ite user. Ite user. Ite user is a substances Ite a substance Ite a substa			



Technical Specifications

Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers .
HP Inc. Corporate	These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. For more information about HP's commitment to the environment:
Information	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SYSTEM UNIT

Stand-Alone Power Requirements (AC

Power)

Nominal Operating Voltage 19V
Average Operating Power Win 10
Integrated graphics 5.71W
Max Operating Power UMA < 45W

Temperature

Operating 32° to 95° F (0° to 35° C) Non-operating -4° to 140° F (-20° to 60° C)

Relative Humidity

Operating 10% to 90%, non-condensing

5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Non-operating

Shock



Technical Specifications

Operating 40 G, 2 ms, half-sine Non-operating 200 G, 2 ms, half-sine

Random Vibration

Operating 0.75 grms
Non-operating 1.50 grms

Altitude (unpressurized)

Operating -50 to 10,000 ft (-15.24 to 3,048 m) Non-operating -50 to 40,000 ft (-15.24 to 12,192 m)

Planned Industry Standard

Certifications

UL Yes
CSA Yes
FCC Compliance Yes

ENERGY STAR® Selected models³⁸

EPEAT Registered Gold in United States³⁹

ICES Yes Australia / Yes **NZ A-Tick Compliance** Yes CCC Yes Japan VCCI Compliance Yes KC Yes **BSMI** Yes **CE Marking Compliance** Yes **BNCI or BELUS** Yes CIT Yes **GOST** Yes

38. Configurations of the HP ProBook 430 G6 that are ENERGY STAR® certified² are identified as HP ProBook 430 G6 ENERGY STAR on HP websites and on http://www.energystar.gov.

39. EPEAT® registered where applicable. EPEAT registration varies by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options.

DISPLAYS

SABS

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 13.3 inch diagonal FHD (1920x1080)

Saudi Arabian Compliance (ICCP)

UKRSERTCOMPUTER

Outline Dimensions (W x H x D)

Active Area

Yes

Yes

Yes

ons (W x H x D) 300.56 x 187.77 max. 293.76 x 165.24 typ.



Technical Specifications

Anti-Glare WLED UWVA 45% cg 220nits eDP slim NB non-touch Weight <260 max.

Diagonal Size 13.3"

Thickness 3.0mm max.
Interface eDP 1.2 (2 lanes)

Surface Treatment Anti-glare

Touch Enabled No

Contrast Ratio 600:1 (typ)
Refresh Rate 60Hz

Brightness 220 nits typical (Panel Only)

Pixel Resolution 1920 x 1080 (FHD)

Format RGB
Backlight LED
Color Gamut Coverage 45%

Color Depth 6 bits (Hi FRC @ system GFX output 8bits)

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch diagonal FHD (1920x1080) WLED UWVA 45% cg 220nits eDP slim NB touch

 Outline Dimensions (W x H x D)
 300.56 x 187.77 max.

 Active Area
 293.76 x 165.24 typ.

Weight <383 max.

Diagonal Size 13.3"

Thickness 3.2mm max.
Interface eDP 1.2 (2 lanes)
Surface Treatment BrightView Glass

Touch Enabled Yes

Contrast Ratio 600:1 (typ)
Refresh Rate 60Hz

Brightness 220 nits typical (Panel Only)

Pixel Resolution 1920 x 1080 (FHD)

Format RGB
Backlight LED
Color Gamut Coverage 45%

Color Depth 6 bits (Hi FRC @ system GFX output 8bits)

Viewing Angle UWVA 85/85/85

Panel LCD 13.3 inch diagonal HD (1366x768) Anti-Glare WLED SVA 45% cg 220nits eDP slim NB non-touch Outline Dimensions (W x H x D) 300.56 x 187.77 max. (w/ PCB & w/o bracket)

Active Area 293.83 x 165.20 typ.

Weight <260 max.

Diagonal Size 13.3 (inch)

Thickness 3.0mm max.

Interface eDP 1.2 (2 lanes)

Surface Treatment Anti-glare

Touch Enabled No



Technical Specifications

Contrast Ratio 300:1 (typ)
Refresh Rate 60Hz

Brightness 220 nits typical (Panel Only)

Pixel Resolution 1366 x 768 (HD)

Format RGB
Backlight LED
Color Gamut Coverage 45%

Color Depth 6 bits (Hi FRC @ system GFX output 8bits)

Viewing Angle SVA 45/45/15/30

Panel LCD 13.3 inch diagonal HD (1366x768) WLED SVA 45% cg 220nits eDP slim NB touch Outline Dimensions (W x H x D) 300.56 x 187.77 max. (w/ PCB & w/o bracket)

Active Area 293.83 x 165.20 typ.

Weight <383 max.

Diagonal Size 13.3 (inch)

Thickness 3.2mm max.

Interface eDP 1.2 (2 lanes)

Surface Treatment BrightView Glass

Touch Enabled Yes

Contrast Ratio 300:1 (typ)
Refresh Rate 60Hz

Brightness 220 nits typical (Panel Only)

Pixel Resolution 1366 x 768 (HD)

Format RGB
Backlight LED
Color Gamut Coverage 45%

Color Depth 6 bits (Hi FRC @ system GFX output 8bits)

Viewing Angle SVA 45/45/15/30

STORAGE AND DRIVES Hard Drives

500 GB 7200 rpm SATA Hard Drive **Drive Weight** 0.20 lbs (92 g) ~ 0.21 lbs (95 g)

Rotation speed7200 rpmCache BufferUp to 32 MBHeight0.28 in (7 mm)Width2.75 in (69.85 mm)InterfaceATA-8, SATA 3.0

Transfer Rate 600 MB/s

Seek Time Single Track: 2 ~ 1.5 ms;

Average: 11 ~ 13 ms; Maximum: 18 ~ 22 ms

Logical Blocks 976,773,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Security Features ATA Security



Technical Specifications

Drive Weight

Features S.M.A.R.T., NCQ, Ultra DMA

1 TB 5400 rpm SATA Hard Drive

Rotation speed 5400 rpm

Cache Buffer Up to 32 MB

Height 0.28 in (7.2 mm)

Width 2.75 in (69.85 mm)

Interface ATA-8, SATA 3.0

Transfer Rate 600 MB/s

Seek Time Single Track2 ms

Average12 ~ 13 ms Maximum18 ~ 22 ms

0.21 lbs (94 q)

Logical Blocks 1,953,525,168

Operating Temperature 32° to 140° F (0° to 60° C) [top cover temp]

Security Features ATA Security

Features S.M.A.R.T., NCQ, Ultra DMA

SSD 128 GB 2280 M2 SATA-3 TLC Form Factor M.2 2280
Capacity 128GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)Weight0.02 lb (10 g)InterfaceATA-8, SATA 3.0Maximum Sequential ReadUp To 520 MB/sMaximum Sequential WriteUp To 450 MB/sLogical Blocks250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features DIPM; TRIM; DEVSLP

256 GB 2280 PCIe NVMe Value Solid State Drive Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3Maximum Sequential ReadUp To 1700 MB/sMaximum Sequential WriteUp to 1300 MB/s



Technical Specifications

Logical Blocks 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

512 GB 2280 M2 PCIe NVMe Form Factor TLC Solid State Drive

Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

Height 0.09 in (2.3 mm)
Width 0.87 in (22 mm)
Interface PCIe NVMe Gen3X4
Maximum Sequential Read Up To 2600 MB/s
Maximum Sequential Write Up To 1400 MB/s
Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features TRIM; L1.2

16 GB 2280 PCIe-3x2 NVMe Form Factor 3D Xpoint Solid State Drive Capacity

Form Factor M.2 2280
Capacity 16 GB
NAND Type Xpoint

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X2

Maximum Sequential Read 1400 Maximum Sequential Write 300

Logical Blocks 28,181,188

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features L1.2

512 GB 2280 PCIe NVMe Value Solid State Drive Form Factor M.2 2280
Capacity 512 GB
NAND Type Value

Height0.09 in (2.3 mm)Width0.87 in (22 mm)InterfacePCIe NVMe Gen3X4Maximum Sequential ReadUp To 1500 ~ 1700 MB/sMaximum Sequential WriteUp To 860 ~ 1500MB/s

Logical Blocks 1,000,215,216

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security, TRIM; L1.2



Technical Specifications

NETWORKING/COMMUNICATIONS

WWAN

Intel® XMM™ 7262 LTE-Advanced DL CAT6¹ Technology/Operating

bands

FDD LTE: 2100 (Band 1), 1800 (Band 3), 850 (Band 5), 2600 (Band 7), 900

(Band 8), 800 (Band 20), 700 (Band 28),

HSPA+: 2100 (Band 1), 850 (Band 5), 900 (Band 8)

Wireless protocol

standards

3GPP Release 11 LTE Specification CAT.6, DL 40MHz BW throughput up to

300Mbps; UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B and XTRA)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz

Maximum data rates LTE: 300 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum power consumption

LTE: 1,200 mA (peak); 830 mA (average)
HSPA+: 1,100 mA (peak); 680 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 g

Dimensions 42 x 30 x 2.3 mm

(Length x Width x Thickness)

1. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

Intel® XMM™ 7360 LTE-Advanced CAT9¹

Technology/Operating

bands

FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3),

1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850

(Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30),

1700/2100 (Band 66).

TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41).

HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4),

850 (Band 5), 900 (Band 8) MHz

Wireless protocol standards

3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to

450Mbps; UL 20MHz throughput up to 50Mbps

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS bands 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz

Maximum data rates LTE: 450 Mbps (Download), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum powerLTE: 1,200 mA (peak); 900 mA (average)consumptionHSPA+: 1,100 mA (peak); 800 mA (average)



Technical Specifications

Form Factor M.2, 3042-S3 Key B

Weight 5.8 g

Dimensions 42 30 x 2.3 mm

(Length x Width x Thickness)

1. WWAN module is optional, must be configured at the factory and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

WLAN

Intel® 9560 802.11a/b/g/n/ac (2x2) WLAN and Bluetooth® 5.0 Combo¹ non-vPro

Wireless LAN Standards

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h
IEEE 802.11i
IEEE 802.11k
IEEE 802.11k

Interoperability Frequency Band Wi-Fi® certified 802.11b/g/n

IEEE 802.11v

• 2.402 - 2.482 GHz

802.11a/n/ac

4.9 – 4.95 GHz (Japan)
5.15 – 5.25 GHz
5.25 – 5.35 GHz
5.47 – 5.725 GHz
5.825 – 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, , 80MHz &

160MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³

- IEEE and WiFi® compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite



Technical Specifications

WAPI

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power²

• 802.11b : +18.5dBm minimum

802.11g: +17.5dBm minimum
802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum

Power Consumption

Transmit mode: 2.0 W

Receive mode: 1.6 W

Idle mode (PSP)180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connected Standby/Modern Standby: 10mW

Radio disabled: 8 mW

Power Management

ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³

802.11b, 1Mbps: -93.5dBm maximum 802.11b, 11Mbps: -84dBm maximum 802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type

High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

HumidityOperating
Non-operating
Operating
10% to 90% (non-condensing)
5% to 95% (non-condensing)

One and the 10 000 ft (2 040 m)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Technical Specifications

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology

Bluetooth® Specification 4.0/4.1/4.2/5.0 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available Legacy: 0~79 (1 MHz/CH) Channels BLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling rate1

> BLE: 1 Mbps signaling data rate1 1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

The Bluetooth component shall operate as a Class II Bluetooth device with **Transmit Power**

a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

USB 2.0 compliant

Selective Suspend 17 mW

Electrical Interface

Bluetooth Software

Supported

Link Topology

Power Management

Certifications

Power Management Certifications

Bluetooth Profiles

Supported

Microsoft Windows ACPI, and USB Bus Support

FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Microsoft Windows Bluetooth Software

ETS 300 328, ETS 300 826

BT4.1-ESR 5/6/7 Compliance

Low Voltage Directive IEC950UL, CSA, and CE Mark

LE Link Layer Ping

LE Dual Mode LE Link Laver

LE Low Duty Cycle Directed Advertising

LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full

LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

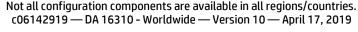
Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Realtek

Wireless LAN Standards IEEE 802.11a

> IEEE 802.11b IEEE 802.11q





Technical Specifications

WLAN and Bluetooth® 4.2 Combo¹

Interoperability Frequency Band IEEE 802.11n IEEE 802.11ac Wi-Fi® certified 802.11b/g/n

•2.402 - 2.482 GHz

802.11a/n

•4.9 – 4.95 GHz (Japan) •5.15 – 5.25 GHz •5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps

802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

802.11ac: MCS0 ~ MCS7. (1SS) (20MHz. 40MHz. and 80MHz)

Modulation

Direct Sequence Spread Spectrum

BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Security³

- IEEE and WiFi® compliant 64 / 128 bit WEP encryption for a/b/g mode only
- AES-CCMP: 128 bit in hardware
- 802.1x authentication
- WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
- WPA2 certification
- IEEE 802.11i
- Cisco Certified Extensions, all versions through CCX4 and CCX Lite
- WAP

Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power²

- 802.11b: +14dBm minimum802.11g: +12dBm minimum
- 802.11a: +12dBm minimum
- 802.11n HT20(2.4GHz): +12dBm minimum
- 802.11n HT40(2.4GHz): +12dBm minimum
- 802.11n HT20(5GHz): +10dBm minimum
- 802.11n HT40(5GHz): +10dBm minimum
- 802.11ac VHT80(5GHz): +10dBm minimum

Power Consumption Transmit: 2.0 W (max)

Receive: 1.6 W (max)

Idle mode (PSP): 180 mW (WLAN Associated)
Idle mode: 50 mW (WLAN unassociated)
Connect Standby: 10 mW (WLAN+BT)

Radio disabled: 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity³ 802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum



Technical Specifications

802.11a/g, 6Mbps: -86dBm maximum 802.11a/g, 54Mbps: -72dBm maximum 802.11n, MCS07: -67dBm maximum 802.11n, MCS15: -64dBm maximum 802.11ac, MCS0: -84dBm maximum 802.11ac, MCS9: -59dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to

support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard

Dimensions Type 2230: 2.3 x 22.0 x 30.0 mm

 Weight
 Type 2230: 2.8g

 Operating Voltage
 3.3v +/- 9%

Temperature Operating 14° to 158° F (–10° to 70° C)

Non-operating -40° to 176° F (-40° to 80° C)

Humidity Operating 10% to 90% (non-condensing)

Non-operating 5% to 95% (non-condensing)

Altitude Operating 0 to 10,000 ft (3,048 m)

Non-operating 0 to 50,000 ft (15,240 m)

LED Activity

LED Amber – Radio OFF; LED White – Radio ON

1. Check latest software/driver release for updates on supported security features.

2. Maximum output power may vary by country according to local regulations.

3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.2 Wireless Technology

Bluetooth® Specification4.0/4.2 CompliantFrequency Band2402 to 2480 MHzNumber of AvailableLegacy: 0~79 (1 MHz/CH)ChannelsBLE: 0~39 (2 MHz/CH)

Signaling Data Rate Legacy: 3 Mbps signaling data rate¹

BLE: 1 Mbps signaling data rate1

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 4 dBm for BR and EDR.

Power Consumption Peak (Tx) 330 mW

Peak (Rx) 230 mW

Selective Suspend 17 mW

Electrical Interface USB 2.0 compliant

Bluetooth Software Microsoft Window

Supported

Microsoft Windows Bluetooth Software



Technical Specifications

Link Topology

Power Management

Certifications

Power Management

Certifications

Bluetooth Profiles Supported

Microsoft Windows ACPI, and USB Bus Support FCC (47 CFR) Part 15C, Section 15.247 & 15.249

ETS 300 328. ETS 300 826

Low Voltage Directive IEC950UL, CSA, and CE Mark

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 –Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)



Technical Specifications

POWER

HP 45W Smart AC Adapter **Dimensions (H x W x D)** 3.74 x 1.57 x 1.04 in (9.5 x 4.0 x 2.65 cm)

Weight 0.386 lb (175g) max

Input 90 to 265 VAC

Input Efficiency 87.74% at 115Vac and 88.4% at 230Vac

Input frequency range 47 to 63 Hz
Input AC current 1.4 A at 90 VAC

Output Output power 45W

DC output 19.5V

Hold-up time 5 msec at 115 VAC input

Output current limit <8.0A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

Environmental Design Operating 32°F to 95°F (0° to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20° to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5,000 m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives

Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B.

FCC Class B. CISPR22 Class B. CCC. NOM-1 NYCE.

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Smart AC Adapter Dimensions 90x51x28.5mm

Weight unit: 220g +/- 10g

Input Efficiency 88% at 115 VAC and 89% at 230 VAC

Input frequency range 47 to 63 Hz
Input AC current 1.7 A at 90 VAC

Output Output power 65W

DC output 19.5V

Hold-up time 5 ms at 115 VAC input

Output current limit <11A

Connector 4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)



Technical Specifications

Humidity 20% to 95%

Storage Humidity 10% to 95%

EMI and Safety Certifications

CE Mark - full compliance with LVD and EMC directives* Worldwide safety standards - IEC60950, EN60950, UL60950, Class 1, SELV: Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B. CISPR22 Class B, CCC, NOM-1 NYCE; MTBF - over 200,000 hours at 25°C

ambient condition.

HP 65W EM Smart AC adapter

Dimensions 102x55x30mm Weight 270a +/- 10a

> **Input Efficiency** 87% min at 115V/230V

Input frequency range 47 to 63 Hz

Input AC current 1.7 A at 90 VAC and maximum load

DC output 65W(19.5V/3.33A) Hold-up time 5 msec at 115 VAC input

<11A. Over voltage protection- 29V max **Output current limit**

automatic shutdown

4.5mm Barrel Type, 3 pin/grounded, mates with interchangeable cords Connector

Environmental Design Operating

temperature

0° to 35° C

Non-operating (storage) -20° to 85° C

temperature

Altitude 0 to 5,000 m **Humidity** 0% to 95% **Storage Humidity** 0% to 95%

EMI and Safety Certifications

CE Mark - full compliance with LVD and EMC directives* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE; MTBF - over 200,000 hours at 25°C

ambient condition.

AC Adapter 65 Watt nPFC Dimensions **USB** type C

Weight

74x74x28.5mm unit: 245q +/- 10q

Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A

86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

47 ~ 63 Hz Input frequency range

1.7 A at 90 VAC and maximum load Input AC current

Output power 65W



Technical Specifications

DC output 5V/9V/10V/12V/15V/20V

Hold-up time 5ms at 115 Vac input

Output current limit <8.0A

Connector Type C

Environmental Design Operating 32°Fto 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Certifications

CE Mark - full compliance with LVD and EMC directives* Worldwide safety standards - IEC60950, EN60950, UL60950, Class 1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B. CISPR22 Class B, CCC, NOM-1 NYCE; MTBF - over 200,000 hours at 25°C

ambient condition.

62.0x62.0x28.5mm

AC Adapter 45 Watt nPFC Dimensions **USB** type C

Weight unit: 220g +/- 10g

> **Input Efficiency** Average Efficiency of 25%, 50%, 75%, 100%

> > load condition with 115Vac/230Vac Spec:5V: 81.5%9V:86.7%10V:87.5%12V:87.8%15V:

87.8%20V:87.8%

Input frequency range 47 ~ 63Hz

Input AC current Max. 1.4 A at 90 Vac

Output power 5V/15W

> 9V/27W 10V/37.5W 12V/45W 15V/45W 20V/45W

DC output 5V / 9V / 10V /12V / 15V / 20V

Hold-up time 5ms at 115 Vac input

Output current limit <5.0A

Connector Type C

Environmental Design Operating 32°F to 95°F (0°to 35°C)

temperature

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95% **Storage Humidity** 10% to 95%



Technical Specifications

EMI and Safety Certifications CE Mark - full compliance with LVD and EMC directives* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE; MTBF - over 200,000 hours at 25°C ambient condition.

3 Cell WHr 45 Long Life -Polymer HP Fast Charge Technology¹
 Dimensions
 6.0. x184.7x88.9 mm

 Weight
 0.22 kg (0.48lb)

Cells/Type 3cell Lithium-Ion

Voltage 11.55V Amp-hour capacity 3.900Ah Watt-hour capacity 45Wh

Operating (Charging) 32° to 113° F (0° to 45° C)
Operating (Discharging) 14° to 122° F (-10° to 60° C)

1. Recharges the battery up to 50% within 30 minutes when the system is off or in standby mode when used with the power adapter provided with the notebook. After charging has reached 50% capacity, charging speed will return to normal. Charging time may vary +/-10% due to System tolerance.

Country of Origin

China



Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case	H2W17AA
	HP Essential Backpack	H1D24AA
	HP Essential Messenger Case	H1D25AA
Docking	HP USB-C Mini Dock	1PM64AA
	HP USB-C Universal Dock	1MK33AA
	HP USB-C Dock G4	3FF69AA
Input/Output	HP USB Essential Keyboard and Mouse	H6L29AA
	HP Ultra Mobile Wireless Mouse	H6F25AA
	HP Comfort Grip Wireless Mouse	H2L63AA
	HP 3-Button USB Laser Mouse	H4B81AA
	HP USB Travel Mouse	G1K28AA
	HP HDMI to DVI Adapter	F5A28AA
Memory	4GB 2666MHz DDR4	4VN05AA
	8GB 2666MHz DDR4	4VN06AA
	16GB 2666 MHz DDR4	4VN07AA
Power	HP 45W Smart AC Adapter 4.5mm	H6Y88AA
	HP 65W Slim AC Adapter	H6Y82AA
	HP 65W USB-C Power Adapter	3PN48AA
	HP 45W USB-C Power Adapter	1HE17AA
	HP 65W USB-C Power Adapter	1HE08AA
	HP Power Bank	N9F71AA
	HP USB-C Power Bank	2NA10AA
	HP 45W LC USB-C Power Adapter	1MZ01AA#ABA
Storage	HP External USB Optical Drive	F2B56AA
	HP 500GB 7200rpm HDD	F3B97AA
Security	HP Combination Lock	TOY15AA
	HP Essential Keyed Cable lock 12.3mm	TOY14AA
	HP Keyed Cable Lock 10mm	T1A62AA
	HP UltraSlim Keyed Cable Lock	T1A62AA
UCC	HP Conferencing Keyboard	K8P74AA
	HP Speaker Phone	K7V16AA
	HP Wired Headset	K7V17AA
Displays	HP ProDisplay P223 21.5-inch Monitor	X7R61AA
	HP ProDisplay P232 23-inch Monitor	K7X31AA
	HP ProDisplay P240va 23.8-inch Monitor	X3B48AA
	HP EliteDisplay E243 23.8-inch Monitor	1FH47AA
	HP EliteDisplay E243m 23.8-inch Collaboration Monitor	1FH48AA
	HP EliteDisplay E273 27-inch Monitor	1FH50AA



Summary of Changes

Date of change:	Version History:		Description of change:
December 10, 2018	V1 to V2	Removed	Dock UltraSlim
December 12, 2018	V2 to V3	Removed	Phonewise Software
December 17, 2018	V3 to V4	Added	Environmental section
December 21, 2018	V4 to V5	Added	Skype in at a glance section
January 30, 2019	V5 to V6	Added	Storage section
March 7, 2019	V6 to V7	Updated	Passed MIL-STD
March 15, 2019	V7 to V8	Added	Processors
March 20, 2019	V8 to V9	Updated	Storage and drives
April 17, 2019	V9 to V10	Updated	MIL-STD

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